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# GaAs MMIC I/Q Mixer 8 - 12 GHz

#### Typical Applications

The HMC1056LP4BE is ideal for:

- Point-to-Point and Point-to-Multi-Point Radio
- Military Radar, EW & ELINT
- Satellite Communications
- Sensors

#### **Features**

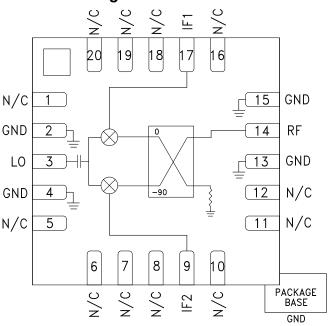
Wide IF Bandwidth: DC - 4 GHz

Image Rejection: 25 dBc LO to RF isolation: 40 dB

High Input IP3: 18 dBm

20 Lead 4x4 mm SMT Package: 16 mm²

#### **Functional Diagram**



#### **General Description**

The HMC1056LP4BE is a compact I/Q MMIC mixer in a leadless "Pb free" SMT package, which can be used as either an Image Reject Mixer or a Single Sideband Upconverter. The mixer utilizes two standard Hittite double balanced mixer cells and a 90 degree hybrid fabricated in a GaAs Schottky diode process. A low frequency quadrature hybrid was used to produce a 100MHz LSB IF output. This product is a much smaller alternative to hybrid style Image Reject Mixers and Single Sideband Upconverter assemblies. The HMC1056LP4BE eliminates the need for wire bonding and allows the use of surface mount manufacturing techniques.

# Electrical Specifications, $T_A = +25$ °C, IF = 100 MHz, LSB, LO = +10 dBm [1]

Parameter	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
Frequency Range, RF/LO		8 - 10			10 - 12		GHz
Frequency Range, IF		DC - 4			DC - 4		GHz
Conversion Loss		8	11		8	11	dB
Image Rejection	18	25		12	18		dBc
LO to RF isolation	33	40		33	40		dB
LO to IF isolation		35			40		dB
IP3 (input)		18			17		dBm
Amplitude Balance [2]		+0.5			+1.5		dB
Phase Balance [2]		+2.5			-2.5		Deg

<sup>[1]</sup> Unless otherwise noted all measurements performed as downconverter.

<sup>[2]</sup> Data taken without external 90° hybrid.

# **HMC1056\* PRODUCT PAGE QUICK LINKS**

Last Content Update: 02/23/2017

# COMPARABLE PARTS -

View a parametric search of comparable parts.

## **EVALUATION KITS**

· HMC1056LP4B Evaluation Board

## **DOCUMENTATION**

#### **Data Sheet**

• HMC1056 Data Sheet

## REFERENCE MATERIALS -

#### **Quality Documentation**

- Package/Assembly Qualification Test Report: LP4, LP4B, LP4C, LP4K (QTR: 2013-00487 REV: 04)
- Semiconductor Qualification Test Report: GaAs SD-A (QTR: 2014-00094)

# DESIGN RESOURCES 🖵

- HMC1056 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

### **DISCUSSIONS**

View all HMC1056 EngineerZone Discussions.

# SAMPLE AND BUY 🖵

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# **TECHNICAL SUPPORT**

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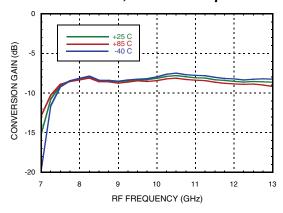




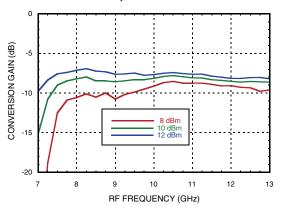
# GaAs MMIC I/Q Mixer 8 - 12 GHz

## Data Taken as SSB Downconverter with External IF 90° Hybrid, IF = 100 MHz

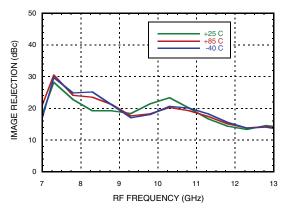
#### Conversion Gain, LSB vs. Temperature



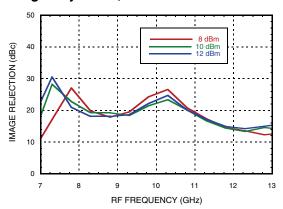
#### Conversion Gain, LSB vs. LO Drive



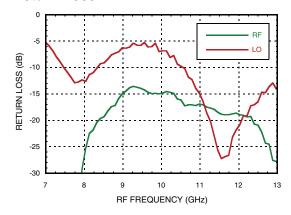
### Image Rejection, LSB vs. Temperature



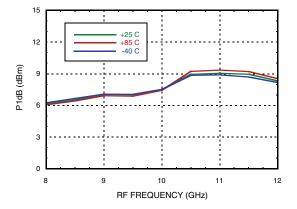
#### Image Rejection, LSB vs. LO Drive



#### **Return Loss**



#### Input P1dB, LSB vs. Temperature



#### [1] Data taken without external IF 90° hybrid

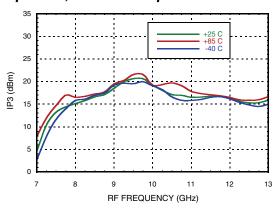




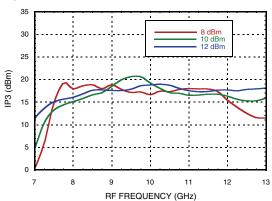
# GaAs MMIC I/Q Mixer 8 - 12 GHz

## Data Taken as SSB Downconverter with External IF 90° Hybrid, IF = 100 MHz

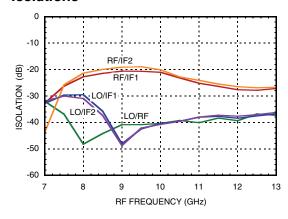
#### Input IP3, LSB vs. Temperature



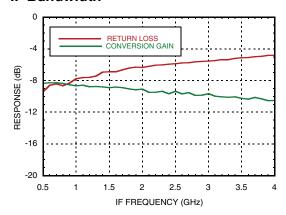
### Input IP3, LSB vs. LO Drive



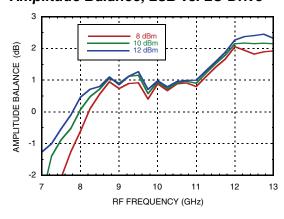
#### Isolations



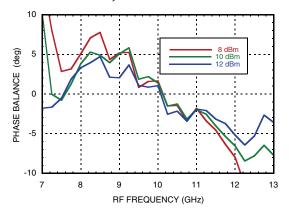
#### IF Bandwidth\*



#### Amplitude Balance, LSB vs. LO Drive



#### Phase Balance, LSB vs. LO Drive



<sup>\*</sup> Conversion gain data taken with external IF hybrid.

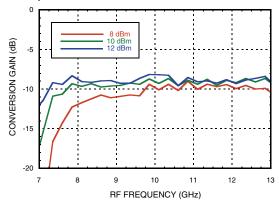




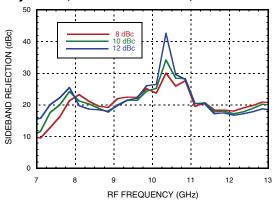
## GaAs MMIC I/Q Mixer 8 - 12 GHz

## Data Taken as SSB Downconverter with External IF 90° Hybrid, IF = 100 MHz

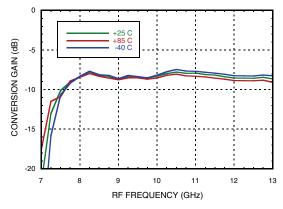
# Upconverter Performance, Conversion Gain, LSB vs. LO Drive



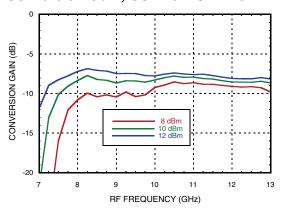
# Upconverter Performance, Sideband Rejection, LSB vs. LO Drive,



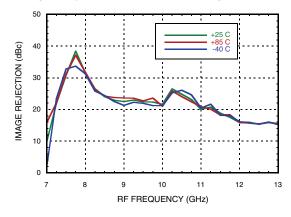
## Conversion Gain, USB vs. Temperature



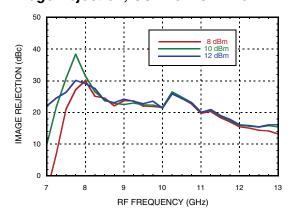
#### Conversion Gain, USB vs. LO Drive



#### Image Rejection, USB vs. Temperature



#### Image Rejection, USB vs. LO Drive



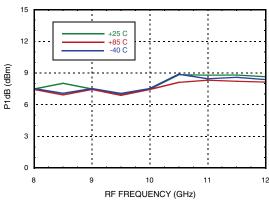




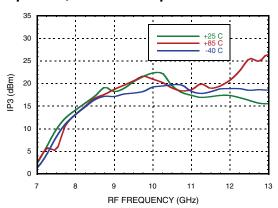
## GaAs MMIC I/Q Mixer 8 - 12 GHz

### Data Taken as SSB Downconverter with External IF 90° Hybrid, IF = 100 MHz

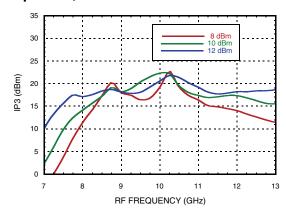
#### Input P1dB, USB vs. Temperature



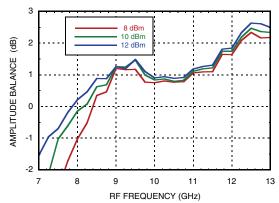
#### Input IP3, USB vs. Temperature



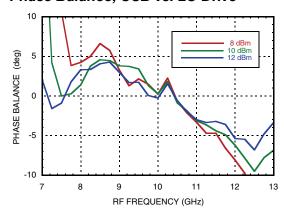
#### Input IP3, USB vs. LO Drive



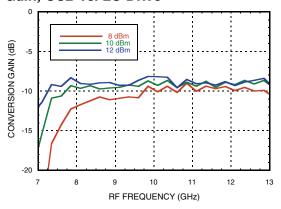
### Amplitude Balance, USB vs. LO Drive



#### Phase Balance, USB vs. LO Drive



# Upconverter Performance, Conversion Gain, USB vs. LO Drive



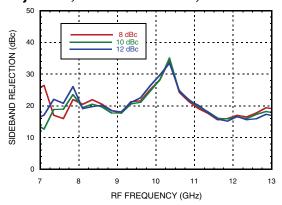




# GaAs MMIC I/Q Mixer 8 - 12 GHz

Data Taken as SSB Upconverter with External IF 90° Hybrid, IF = 100 MHz

# Upconverter Performance, Sideband Rejection, USB vs. LO Drive,



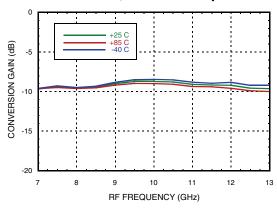




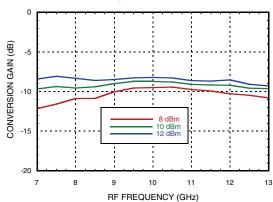
## GaAs MMIC I/Q Mixer 8 - 12 GHz

### Data Taken as SSB Downconverter with External IF 90° Hybrid, IF = 1000 MHz

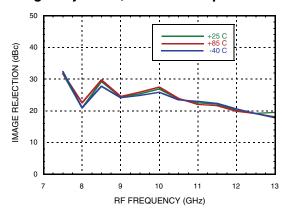
#### Conversion Gain, LSB vs. Temperature



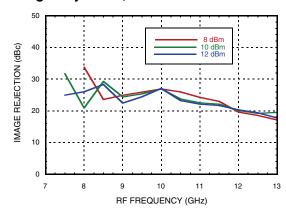
#### Conversion Gain, LSB vs. LO Drive



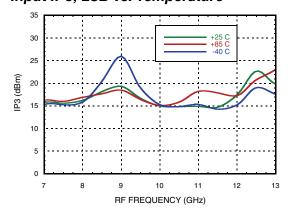
#### Image Rejection, LSB vs. Temperature



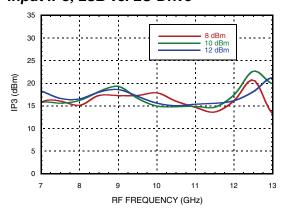
#### Image Rejection, LSB vs. LO Drive



#### Input IP3, LSB vs. Temperature



Input IP3, LSB vs. LO Drive

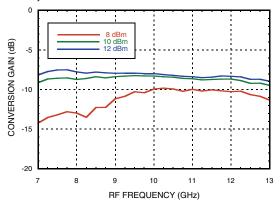




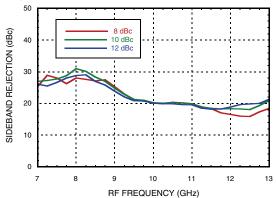
## GaAs MMIC I/Q Mixer 8 - 12 GHz

### Data Taken as SSB Downconverter with External IF 90° Hybrid, IF = 1000 MHz

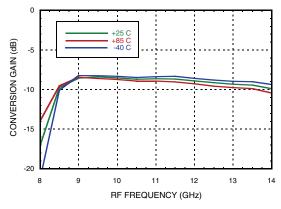
# Upconverter Performance, Conversion Gain, LSB vs. LO Drive



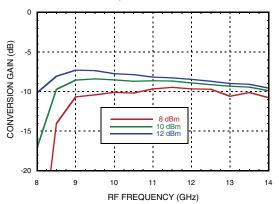
# Upconverter Performance, Sideband Rejection, LSB vs. LO Drive,



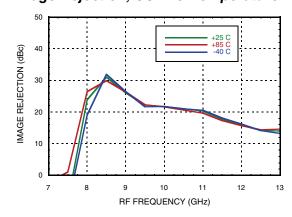
## Conversion Gain, USB vs. Temperature



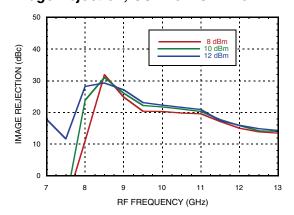
#### Conversion Gain, USB vs. LO Drive



#### Image Rejection, USB vs. Temperature



#### Image Rejection, USB vs. LO Drive



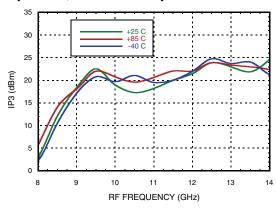




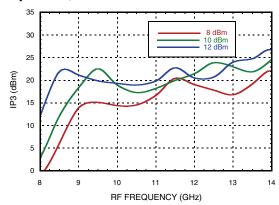
# GaAs MMIC I/Q Mixer 8 - 12 GHz

### Data Taken as SSB Downconverter with External IF 90° Hybrid, IF = 1000 MHz

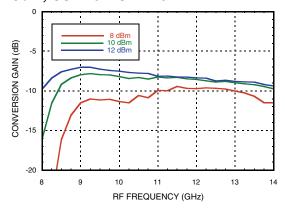
#### Input IP3, USB vs. Temperature



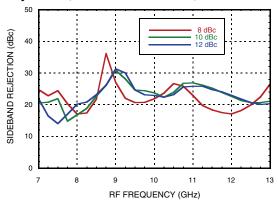
#### Input IP3, USB vs. LO Drive



# Upconverter Performance, Conversion Gain, USB vs. LO Drive



# Upconverter Performance, Sideband Rejection, USB vs. LO Drive,

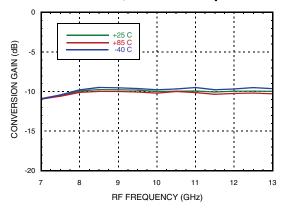




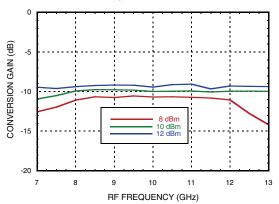
# GaAs MMIC I/Q Mixer 8 - 12 GHz

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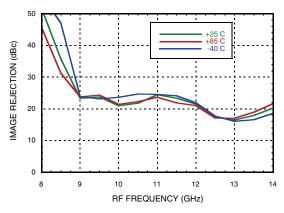
#### Conversion Gain, LSB vs. Temperature



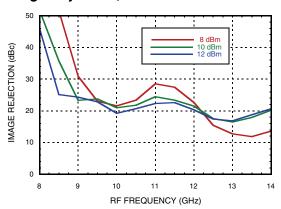
#### Conversion Gain, LSB vs. LO Drive



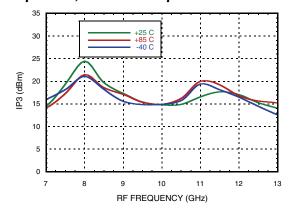
### Image Rejection, LSB vs. Temperature



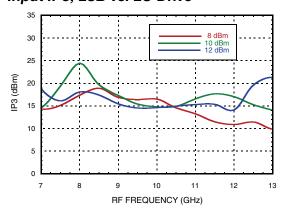
#### Image Rejection, LSB vs. LO Drive



## Input IP3, LSB vs. Temperature



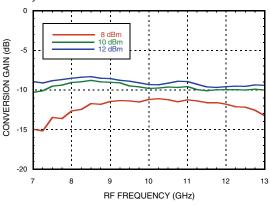
#### Input IP3, LSB vs. LO Drive



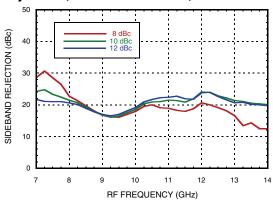
# GaAs MMIC I/Q Mixer 8 - 12 GHz

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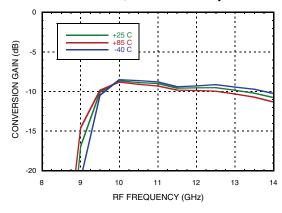
# Upconverter Performance, Conversion Gain, LSB vs. LO Drive



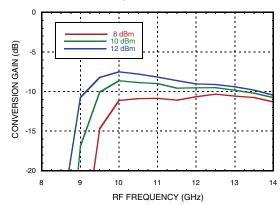
# Upconverter Performance, Sideband Rejection, LSB vs. LO Drive,



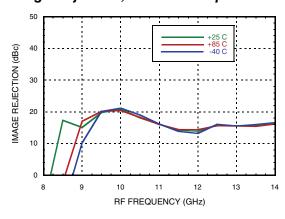
#### Conversion Gain, USB vs. Temperature



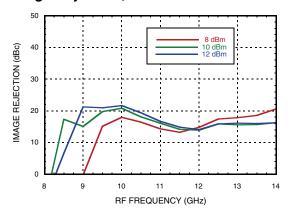
#### Conversion Gain, USB vs. LO Drive



#### Image Rejection, USB vs. Temperature



#### Image Rejection, USB vs. LO Drive

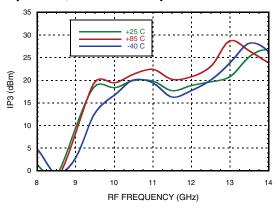




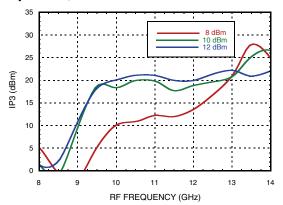


# GaAs MMIC I/Q Mixer 8 - 12 GHz

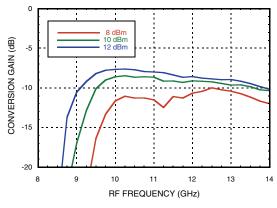
#### Input IP3, USB vs. Temperature



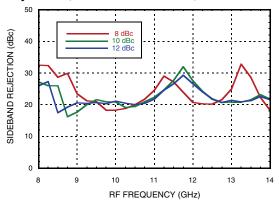
#### Input IP3, USB vs. LO Drive



# Upconverter Performance, Conversion Gain, USB vs. LO Drive



# Upconverter Performance, Sideband Rejection, USB vs. LO Drive,



#### Harmonics of LO

LO Erog (CHz)	nLO Spur at RF Port				
LO Freq. (GHz)	1	2	3	4	
7	41.3	37.6	74.4	74.2	
8	36.3	36.3	52	82.1	
9	37.2	52.9	63.6	81.4	
10	36.8	56.4	65.5	100.4	
11	37.3	59.8	68.9	68.8	
12	37.4	56.2	65.3	78.9	
13	38.1	56.4	69.6	х	

LO = + 10 dBm

Values in dBc below LO level measured at RF Port.

### **MxN Spurious Outputs**

	nLO				
mRF	0	1	2	3	4
0	xx	8	38	48	60
1	8	0	28	43	60
2	64	50	56	48	67
3	94	78	67	64	78
4	х	х	х	х	х

RF = 10 GHz @ -10 dBm

LO = 10.1 GHz @ +10 dBm

Data taken without IF hybrid

All values in dBc below IF power level





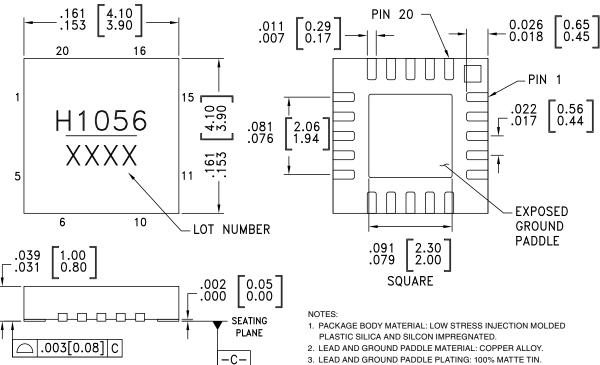
GaAs MMIC I/Q Mixer 8 - 12 GHz

## **Absolute Maximum Ratings**

IF Input (At LO = 10 dBm and RF = -10 dBm)	+15.5 dBm	
RF Input (At 10 dBm LO power)	+16 dBm	
LO Input (At -10 dBm RF power)	+17 dBm	
Channel Temperature	175 °C	
Continuous Pdiss (T = 85°C) (derate 8.9 mW/°C above 85°C)	800 mW	
Thermal Resistance (channel to ground paddle)	112 °C/W	
Storage Temperature	-65 to +150 °C	
Operating Temperature	-40 to +85 °C	
ESD Sensitivity (HBM)	Class 0, Passed 150V	



## **Outline Drawing**



- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 5. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 6. PAD BURR LENGTH SHALL BE 0.15mm MAX. PAD BURR HEIGHT SHALL BE 0.05mm MAX.
- PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 8. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

#### Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating [2]	Package Marking [1]
HMC1056LP4BE	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1	H1056 XXXX

<sup>[1] 4-</sup>Digit lot number XXXX

[2] Max peak reflow temperature of 260 °C





# GaAs MMIC I/Q Mixer 8 - 12 GHz

### **Pin Descriptions**

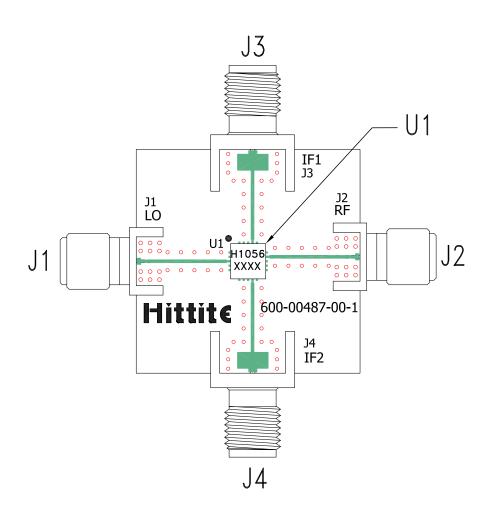
Pin Number	Function	Description	Interface Schematic
1, 5-8, 10-12, 16, 18-20	N/C	These pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
2, 4, 13, 15	GND	These pins and the exposed ground paddle must be connected to RF/DC ground.	○ GND =
3	LO	This pin is AC coupled and matched to 50 Ohms .	L0 ○────
9	IF2	Differential IF input pins. For applications not requiring operation to DC, an off chip DC blocking capacitor should	IF1,IF2 O
17	IF1	be used. For operation to DC this pin must not source/sink more than 3mA of current or part non function and possible part failure will result.	
14	RF	This pin is matched to 50 Ohms.	RF ○





## GaAs MMIC I/Q Mixer 8 - 12 GHz

#### **Evaluation PCB**



#### List of Materials for Evaluation PCB EVAL01-HMC1056LP4B[1]

Item	Description
J1, J2	PCB Mount SMA RF Connector, SRI
J3 - J4	PCB Mount SMA Connector, Johnson
U1	HMC1056LP4BE
PCB [2]	600-00487-00-1 Evaluation Board

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

<sup>[2]</sup> Circuit Board Material: Rogers 4350



MIXERS - I/Q MIXERS, IRMS & RECEIVERS - SMT





Notes:

GaAs MMIC I/Q Mixer 8 - 12 GHz